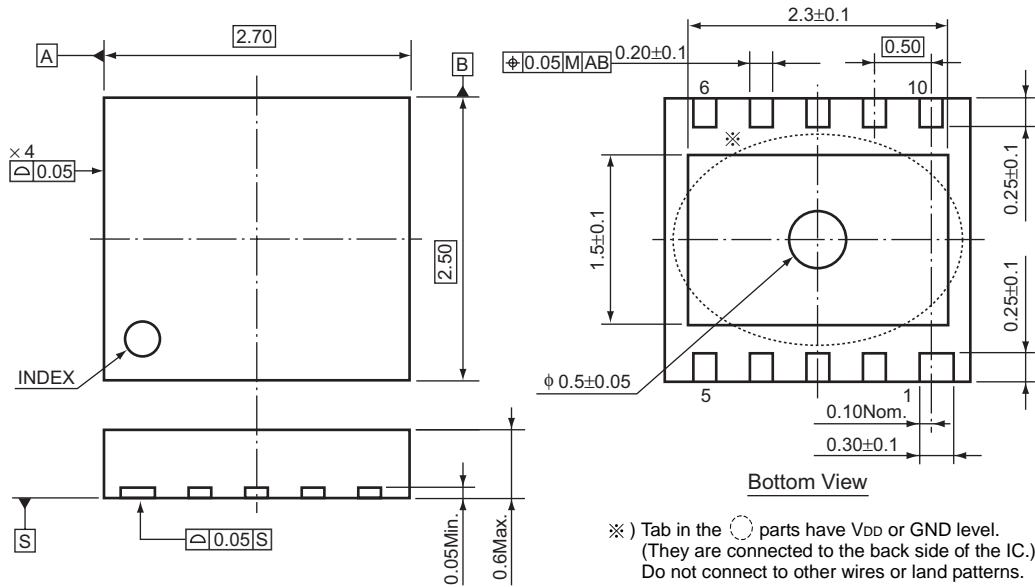


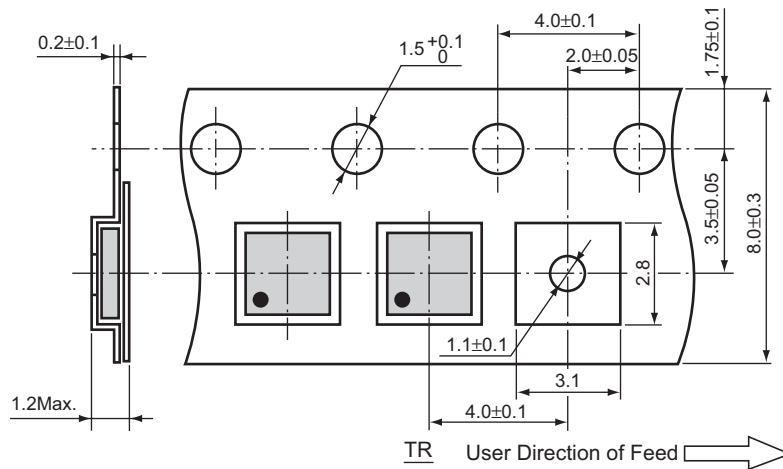
• DFN(PLP)2527-10

Unit: mm

PACKAGE DIMENSIONS

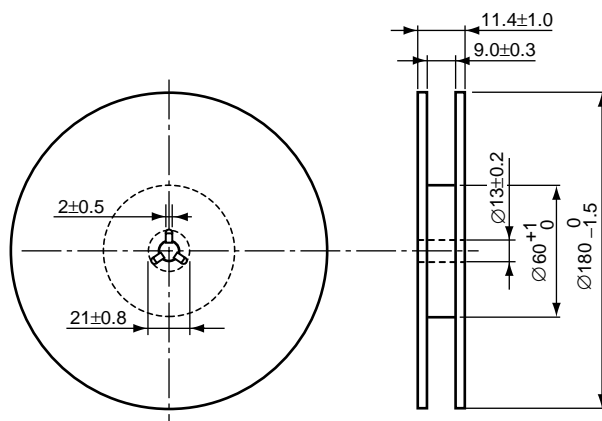


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1 reel=5,000 pcs)



### POWER DISSIPATION (DFN(PLP)2527-10)

This specification is at mounted on board. Power Dissipation (P<sub>D</sub>) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

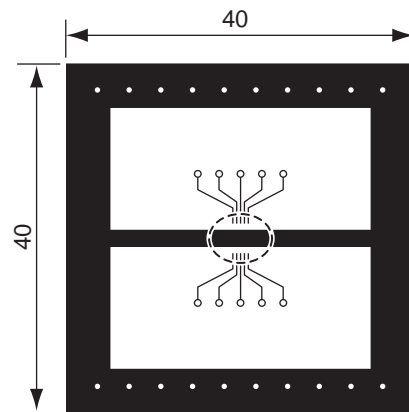
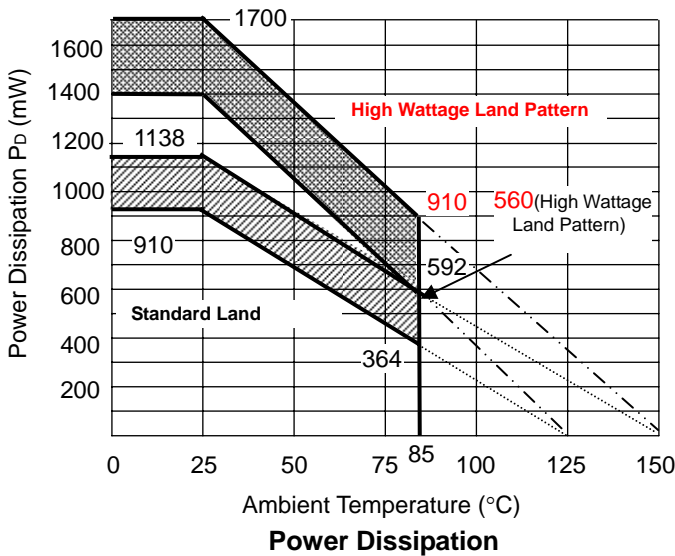
Measurement Conditions

	High Wattage Land Pattern	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (4-Layers)	Glass cloth epoxy plastic (Double sided)
Board Dimensions	35mm × 90mm × 0.8mm	40mm × 40mm × 1.6mm
Copper Ratio	Each layers : Approx. 15%	Top side : Approx. 50% , Back side : Approx. 50%
Through-holes	φ0.3mm × 9pcs, φ0.5mm × 10pcs	φ0.54mm × 30pcs

Measurement Results

(T<sub>opt</sub>=25°C, T<sub>jmax</sub>=125°C)

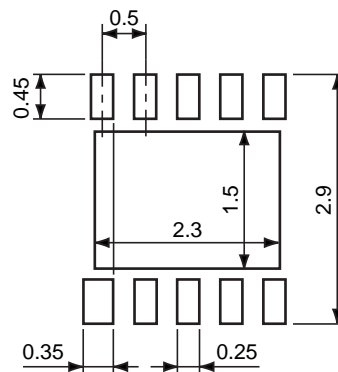
	High Wattage Land Pattern	Standard Land Pattern
Power Dissipation	1400mW	910mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/1.4\text{W}=71^{\circ}\text{C/W}$	$\theta_{ja}=(125-25^{\circ}\text{C})/0.91\text{W}=110^{\circ}\text{C/W}$
	$\theta_{jc}=14^{\circ}\text{C/W}$	$\theta_{jc}=20^{\circ}\text{C/W}$



Measurement Board Pattern

○ IC Mount Area (Unit: mm)

### RECOMMENDED LAND PATTERN



(Unit: mm)

The above graph shows the Power Dissipation of the package based on T<sub>jmax</sub>=125°C and T<sub>jmax</sub>=150°C.

Operating the IC in the shaded area in the graph might have an influence it's lifetime.

Operating time must be within the time limit described in the table below, in case of operating in the shaded area.

Product Name	Operating time	Estimated years*
RP901K	13,000 hrs	9 years

\*The volume is calculated on the supposition that operating four hours/day.